

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): H. MAEJIMA ET AL.

Serial No. : Not Assigned Yet
(Reissue of Patent No.: 5,230,747
Issued: July 27, 1993)

Filed: November 3, 2000

For: WAFER HAVING CHAMFERED BEND PORTIONS IN THE
JOINT REGIONS BETWEEN THE CONTOUR OF THE WAFER
AND THE CUT-AWAY PORTION OF THE WAFER

INFORMATION DISCLOSURE STATEMENT
UNDER 37 CFR §1.97 & §1.98

Assistant Commissioner of Patents
Washington, D.C. 20231

November 3, 2000

Sir:

In the matter of the reissue application for the above-identified patent, applicants are submitting herewith a copy of an official action from a foreign patent office in a counterpart foreign application, an English translation of the official action and copies of the documents cited therein which have also been listed in the attached form equivalent to Form PTO-1449 for the Examiner's consideration.

An English translation of the cited German language patent specification DD 148,997 is also enclosed.

This information disclosure statement is being submitted at the time of filing of this reissue application.

Each of the documents listed on the attached Form PTO-1449 is referred to in the official action.

Please charge any shortage in the fees due in connection with the filing of this paper, including extension of time

fees, to Deposit Account No. 01-2135 (501.20289RC6) and please credit any excess fees to such deposit account.

Respectfully submitted,

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